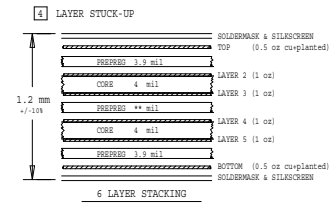


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (single end)	IMPEDANCE (differential)	TOLERANCE
1,6 4	5.0 4.0	N/A	55 OHM	N/A	+/-10%
1,6	5.1	9.9	N/A	100 OHM	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%

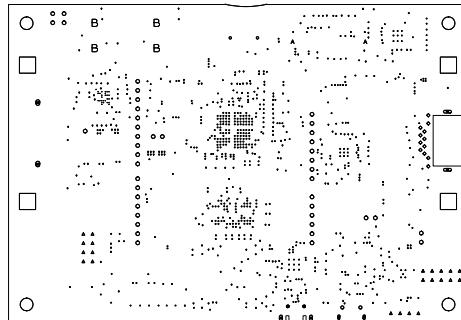


PCB SPECIFICATIONS:

- | | | | | |
|-----------------------|---|--|--|---------------------------------|
| A. MATERIAL; | FR-4, | <input checked="" type="checkbox"/> TG-170 | <input type="checkbox"/> TG-150 | <input type="checkbox"/> TG-140 |
| B. MATERIAL FAMILY; | N/A. | | | |
| C. SOLDERMASK COLOR; | <input checked="" type="checkbox"/> GREEN | <input type="checkbox"/> BLUE | <input type="checkbox"/> RED | <input type="checkbox"/> BLACK |
| D. SILKSCREEN COLOR; | <input checked="" type="checkbox"/> WHITE | <input type="checkbox"/> YELLOW | <input type="checkbox"/> BLACK | |
| E. SURFACE FINISH; | <input checked="" type="checkbox"/> ENIG | <input type="checkbox"/> IMMERSION SILVER | <input type="checkbox"/> IMMERSION TIN | |
| | <input type="checkbox"/> HASL | <input type="checkbox"/> HASL (PB-FREE) | <input type="checkbox"/> GOLDEN FINGER | |
| F. IMPEDANCE CONTROL; | <input type="checkbox"/> NO | <input checked="" type="checkbox"/> YES | (SEE IMPEDANCE TABLE FOR DETAILED INFORMATION) | |
| G. THROUGH VIA; | PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDES. | | | |
| | PLUG MATERIAL: <input checked="" type="checkbox"/> SOLDERMASK | | <input type="checkbox"/> NON-CONDUCTIVE EPOXY. | |
| H. STACK-UP; | SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS. | | | |


PCB REQUIREMENTS:

1. THIS BOARD WILL CONFORM TO:
IPC-A-600, CURRENT REV., CLASS II
IPC-6012, CURRENT REV., CLASS II
2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
3. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM
AVERAGE, WITH NO READING LESS THAN .0008 BY COROSSE SECTION.
4. MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
5. BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER
IPC-SM-840 CLASS II.
6. SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP
ON ANY COMPONENT PAD OR THROUGH HOLE.
7. MFGPR, TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK
A. U.I. CODE D. MFGPR. LOGO
B. DATE CODE E. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
8. REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
9. REMOVE ALL SHAPE EDGES AND BURS. .005 MAXIMUM.
10. PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE
FABRICATING BOARD.



DRILL CHART: TOP TO BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	ROTATION	QT
•	6.0	+3.0/-3.0	PLATED	-	27
•	8.0	+3.0/-3.0	PLATED	-	21
•	10.0	+3.0/-3.0	PLATED	-	35
•	12.0	+3.0/-3.0	PLATED	-	34
•	33.0	+3.0/-3.0	PLATED	-	2
•	35.0	+5.0/-5.0	PLATED	-	12
•	36.0	+3.0/-3.0	PLATED	-	27
•	40.0	+3.0/-3.0	PLATED	-	43
○	138.0	+3.0/-3.0	PLATED	-	4
□	177.0	+3.0/-3.0	PLATED	-	4
•	28.0	+2.0/-2.0	NON-PLATED	-	2
•	40.0	+2.0/-2.0	NON-PLATED	-	2
B	79.0	+2.0/-2.0	NON-PLATED	-	4
•	33.0x30.0	+5.0/-5.0	PLATED	90.000	2
•	51.0x24.0	+5.0/-5.0	PLATED	90.000	2
•	58.0x42.0	+5.0/-5.0	PLATED	90.000	2
•	59.0x33.0	+5.0/-5.0	PLATED	90.000	2
•	87.0x28.0	+5.0/-5.0	PLATED	0.000	2

TOTAL HOLES: 1054

 <p>DESIGNED BY SOFER www.sofer.com.cn</p> <p>Tel : +86 21 - 6482 6908 Mail: designs@sofer.com.cn</p>	<p>LAYER: FAB DAWNING & DRILL LEGEND</p>	<p>COMPANY NAME: ST</p>	
	<p>DESIGNER: Shelley</p>	<p>PROJECT NAME: MB1225</p>	
	<p>DATE: 2016.02.22</p>	<p>PROJECT NUMBER: D031-01922</p>	<p>REV</p>

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	LOGO		COMPANY NAME	
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +	DRAWN	YY-MM-DD	TITLE PROJECT NAME *			
	CHECKED	YY-MM-DD				
	ENGRG	YY-MM-DD				
	ISSUED					
			SIZE B	DWG NO	*****	REV **
			SCALE 1:1		SHEET	1 OF 1